

2.8X0.8mm RIGHT ANGLE SMD CHIP LED **LAMP**

Part Number: KA-2810AQBS-D Blue



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE

DEVICES

Features

- 2.8mmX0.8mm right angle SMT LED, 1.2mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

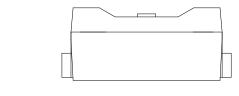
The Blue source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

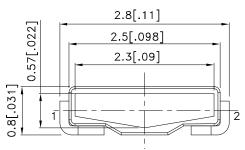
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

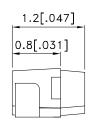
All devices, equipment and machinery must be electrically grounded.

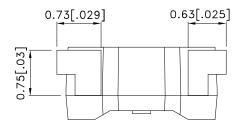
Package Dimensions

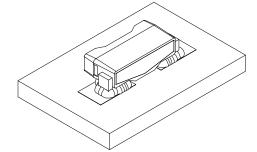












- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.0039") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

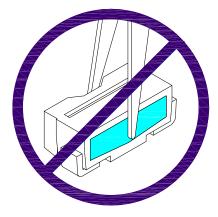
 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



2. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
KA-2810AQBS-D	A-2810AQBS-D Blue (InGaN)		80	150	110°

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity/ luminous Flux: +/-15%.
 Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.		Тур.		Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	468	*460		nm IF=20mA			
λD [1]	Dominant Wavelength	Blue	470	*465		nm	IF=20mA		
Δλ1/2	Spectral Line Half-width	Blue	25			nm	IF=20mA		
С	Capacitance	Blue	100			pF	V _F =0V;f=1MHz		
VF [2]	Forward Voltage	Blue	3.3		3.3 4 V		IF=20mA		
lr	Reverse Current	Blue			50	uA	V _R =5V		

Notes:

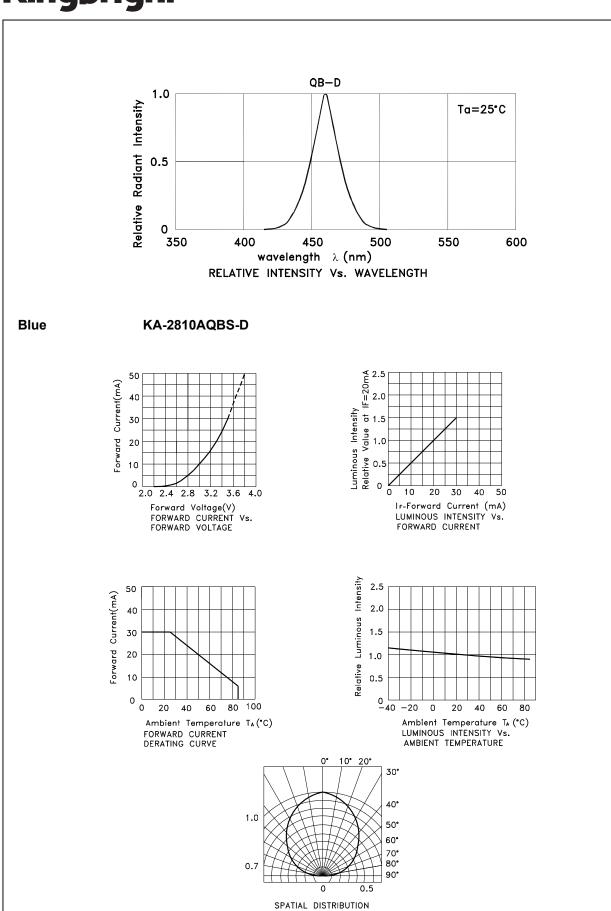
Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Units		
Power dissipation	120	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

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^{1.}Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
*Wavelength value is traceable to the CIE127-2007 compliant national standards.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

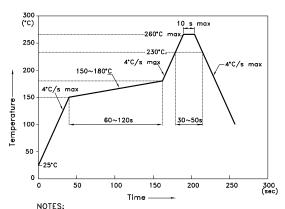


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KA-2810AQBS-D

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

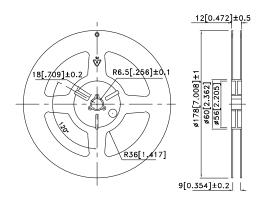
 3.Number of reflow process shall be 2 times or less.

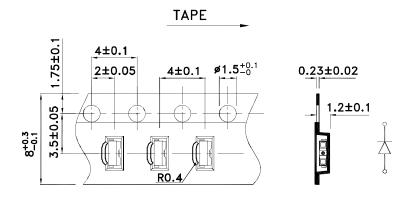
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

0.5 0.5

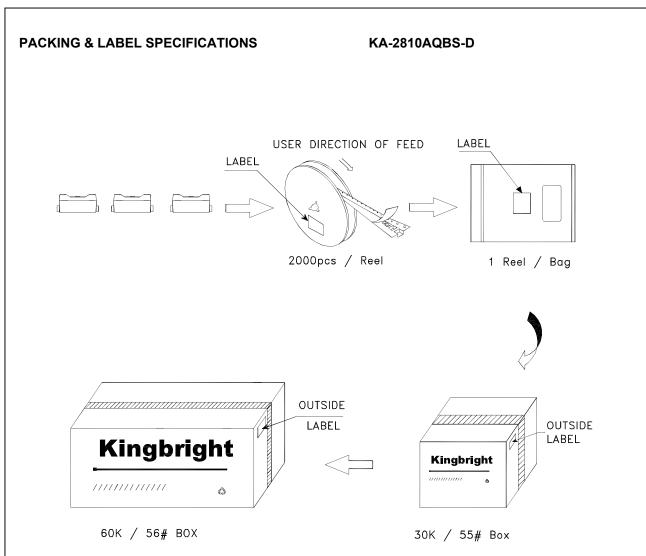
Tape Dimensions (Units: mm)

Reel Dimension





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